&TDK

SMD Inductors(Coils) For Signal Line(Multilayer, Magnetic Shielded)

Conformity to RoHS Directive

MLF Series MLF2012-J

Since digital devises have become faster and have more functions, stricter inductance tolerance has become necessary in the high frequency range.

The ferrite material and internal electrodes for MLF2012-J tolerance products have been newly developed and have received optimal process design. As a result, tolerance could be narrowed (±5%) to half of the previous MLF series, and drift variance was also been greatly improved.

FEATURES

- Inductance tolerance is ±5% (J-tolerance)
- Temperature stress (drift variance percentage) for soldering is ±3%, which is an improvement of 1/3 over the previous product.
- The products contain no lead and also support lead-free soldering.
- It is a product conforming to RoHS directive.

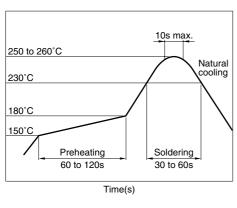
APPLICATIONS

Signal processing such as car audio, automotive (intended) use, tuner.

SPECIFICATIONS

Operating temperature range	−55 to +125°C
Storage temperature range	−55 to +125°C

RECOMMENDED SOLDERING CONDITION REFLOW SOLDERING



PRODUCT IDENTIFICATION

 $\frac{\text{MLF}}{(1)} \frac{2012}{(2)} \frac{\text{A}}{(3)} \frac{1\text{R0}}{(4)} \frac{\text{J}}{(5)} \frac{\text{T}}{(6)}$

- (1) Series name
- (2) Dimensions L×W

2012	2.0×1.25mm	

- (3) Material code
- (4) Inductance value

R10	0.1μΗ
1R0	1.0μΗ
100	10μΗ

(5) Inductance tolerance

J	±5%

(6) Packaging style

_	T : E 0
I	Taping [reel]

PACKAGING STYLE AND QUANTITIES

Packaging style	Product's thickness T	Quantity
Taping	0.85mm	4000 pieces/reel
	1.25mm	2000 pieces/reel

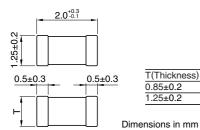
HANDLING AND PRECAUTIONS

- Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and product temperature does not exceed 150°C.
- After mounting components onto the printed circuit board, do not apply stress through board bending or mishandling.
- The inductance value may change due to magnetic saturation if the current exceeds the rated maximum.
- · Do not expose the inductors to stray magnetic fields.
- · Avoid static electricity discharge during handling.
- When hand soldering, apply the soldering iron to the printed circuit board only. Temperature of the iron tip should not exceed 350°C. Soldering time should not exceed 3 seconds.

- Conformity to RoHS Directive: This means that, in conformity with EU Directive 2002/95/EC, lead, cadmium, mercury, hexavalent chromium, and specific bromine-based flame retardants, PBB and PBDE, have not been used, except for exempted applications.
- Please contact our Sales office when your application are considered the following:
 The device's failure or malfunction may directly endanger human life (e.g. application for automobile/aircraft/medical/nuclear power devices, etc.)

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SHAPES AND DIMENSIONS/RECOMMENDED PC BOARD PATTERN



T(Thickness)	Weight(mg)
0.85±0.2	10
1.25±0.2	14



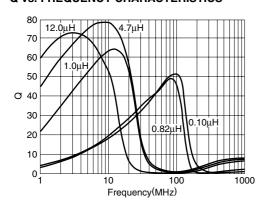


ELECTRICAL CHARACTERISTICS

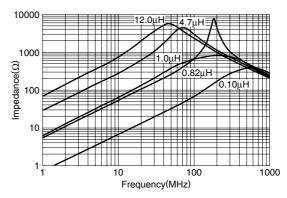
Inductance	Inductance	Q		Test	Test	Self-re	sonant	DC res	sistance	Rated	Thickness	
(μH)	tolerance	Q 		frequency current		freque	frequency (MHz) (Ω)			current	Т	Part No.
(μπ)	tolerance	min.	typ.	L, Q (MHz)	L, Q (mA)	min.	typ.	max.	typ.	(mA)max.	(mm)	
0.1	±5%	20	30	25	1.0	400	500	0.15	0.10	300	0.85±0.2	MLF2012DR10J
0.12	±5%	20	30	25	1.0	360	450	0.20	0.12	300	0.85±0.2	MLF2012DR12J
0.15	±5%	20	30	25	1.0	320	410	0.20	0.13	300	0.85±0.2	MLF2012DR15J
0.18	±5%	20	30	25	1.0	280	370	0.25	0.15	300	0.85±0.2	MLF2012DR18J
0.22	±5%	20	30	25	1.0	250	330	0.30	0.16	250	0.85±0.2	MLF2012DR22J
0.27	±5%	20	30	25	1.0	220	300	0.35	0.18	250	0.85±0.2	MLF2012DR27J
0.33	±5%	20	30	25	1.0	200	270	0.40	0.23	250	0.85±0.2	MLF2012DR33J
0.39	±5%	25	35	25	1.0	180	250	0.45	0.25	200	0.85±0.2	MLF2012DR39J
0.47	±5%	25	35	25	1.0	160	230	0.50	0.25	200	1.25±0.2	MLF2012DR47J
0.56	±5%	25	35	25	1.0	150	210	0.55	0.30	150	1.25±0.2	MLF2012DR56J
0.68	±5%	25	35	25	1.0	140	190	0.60	0.35	150	1.25±0.2	MLF2012DR68J
0.82	±5%	25	35	25	1.0	130	170	0.65	0.40	150	1.25±0.2	MLF2012DR82J
1	±5%	45	55	10	1.0	120	160	0.30	0.15	80	0.85±0.2	MLF2012A1R0J
1.2	±5%	45	55	10	1.0	110	150	0.35	0.15	80	0.85±0.2	MLF2012A1R2J
1.5	±5%	45	60	10	1.0	100	140	0.40	0.18	80	0.85±0.2	MLF2012A1R5J
1.8	±5%	45	60	10	1.0	90	130	0.45	0.20	80	0.85±0.2	MLF2012A1R8J
2.2	±5%	45	60	10	1.0	80	120	0.50	0.22	50	0.85±0.2	MLF2012A2R2J
2.7	±5%	45	70	10	1.0	70	100	0.55	0.25	50	1.25±0.2	MLF2012A2R7J
3.3	±5%	45	70	10	1.0	60	90	0.60	0.28	50	1.25±0.2	MLF2012A3R3J
3.9	±5%	45	70	10	1.0	55	80	0.65	0.30	30	1.25±0.2	MLF2012A3R9J
4.7	±5%	45	70	10	1.0	50	70	0.70	0.35	30	1.25±0.2	MLF2012A4R7J
5.6	±5%	50	75	4	0.1	45	65	0.60	0.30	15	1.25±0.2	MLF2012E5R6J
6.8	±5%	50	75	4	0.1	40	60	0.65	0.32	15	1.25±0.2	MLF2012E6R8J
8.2	±5%	50	75	4	0.1	35	55	0.70	0.35	15	1.25±0.2	MLF2012E8R2J
10	±5%	50	75	2	0.1	30	50	0.80	0.40	15	1.25±0.2	MLF2012E100J
12	±5%	50	75	2	0.1	25	45	0.90	0.50	15	1.25±0.2	MLF2012E120J

• Test equipment Inductance, Q: Ag4294A-16034G

TYPICAL ELECTRICAL CHARACTERISTICS Q vs. FREQUENCY CHARACTERISTICS

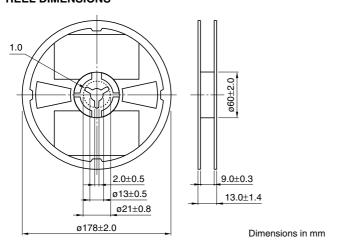


IMPEDANCE vs. FREQUENCY CHARACTERISTICS



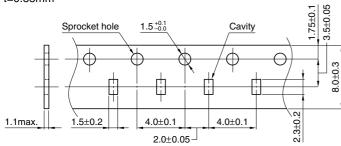
[•] All specifications are subject to change without notice.

PACKAGING STYLES REEL DIMENSIONS

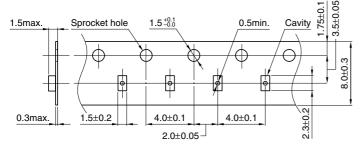


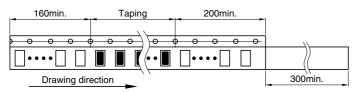
TAPE DIMENSIONS

t=0.85mm



t=1.25mm





Dimensions in mm

[•] All specifications are subject to change without notice.